

**Search Notes**

Application No.

10/649,123

Examiner

Stephen W. Smoot

Applicant(s)

KATZ, ANNE T.

Art Unit

2813

**SEARCHED**

Class	Subclass	Date	Examiner
257	686	3/3/2004	SWS
257	697	3/3/2004	SWS
257	723	3/3/2004	SWS
257	725	3/3/2004	SWS
257	777	3/3/2004	SWS
257	784	3/3/2004	SWS
257	789	3/3/2004	SWS
257	795	3/3/2004	SWS
438	109	3/3/2004	SWS
Updated	Above	10/15/2004	SWS

**INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner
Same as Above		10/15/2004	SWS

**SEARCH NOTES  
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Considered all references cited in parent application.	3/3/2004	SWS
Key Words: Package Substrate, Wiring Substrate, Chip Carrier, Multichip Module -MCM;	3/3/2004	SWS
COC - Chip-on-Chip, Chip-Over-Chip, Stacked Chip;	3/3/2004	SWS
Encapsulant, Adhesive, Silver-Filled, Tape; Wire Bonding, Bond Wires	3/3/2004	SWS
Updated Above Search	10/15/2004	SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	3/3/2004 10-15-04	SWS